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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









Technical Data Sheet

1.6mm Round Subminiature Reverse package Chip LED

26-21UYC/S530-A3/TR8

Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

- The 26-21 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

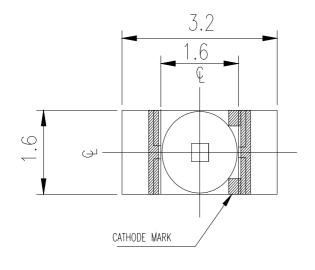
Part No.		Chip	F 1.G.1	Resin Color	
		Material	Emitted Color		
26-21UY	C/S530-A3/TR8	AlGaInP	Brilliant Yellow	Water Clear	

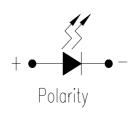


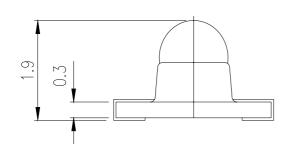
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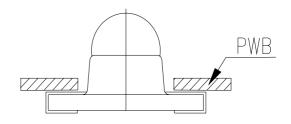
Device No.: SZDSE-261- Prepared date: 8-Apr -2009 Prepared by: Huangyongxin

Package Outline Dimensions

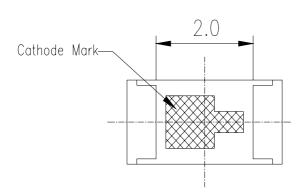


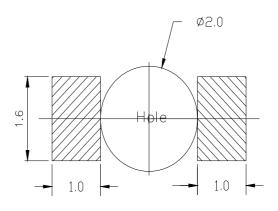






For Reflow Soldering (Propose)





Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

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Absolute Maximum Ratings (Ta=25 $^{\circ}$ C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	VR	10	V
Forward Current	${ m I}_{ m F}$	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	Ifp	60	mA
Power Dissipation	Pd	60	mW
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\!\mathbb{C}$
Soldering Temperature	Tsol	Reflow Soldering: 260 °C for 10 se Hand Soldering: 350 °C for 3 sec.	

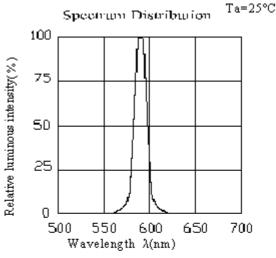
Electro-Optical Characteristics (Ta=25°C)

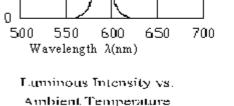
_	I	1	1	I		1
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	Iv	240	400		mcd	
Viewing Angle	2 θ 1/2		30		deg	
Peak Wavelength	λр		591		nm	
Dominant Wavelength	λd		589		nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ		15		nm	
Forward Voltage	VF	1.7	2.0	2.4	V	
Reverse Current	Ir			10	μ A	V _R =5V

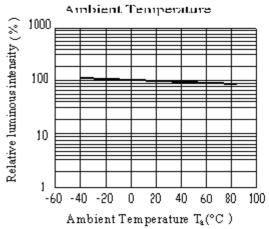
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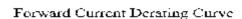
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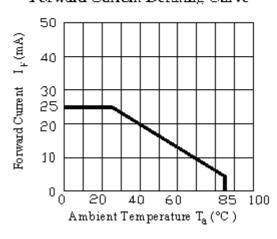
Typical Electro-Optical Characteristics Curves

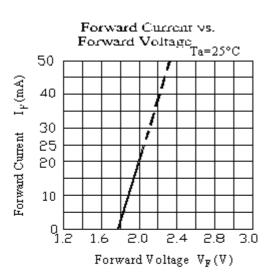


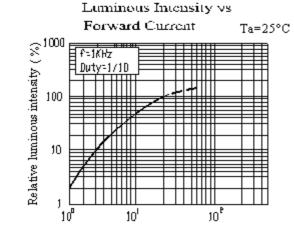


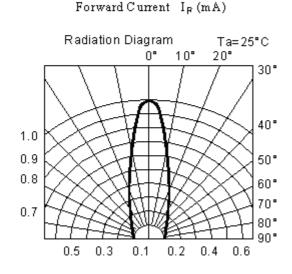












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Label explanation

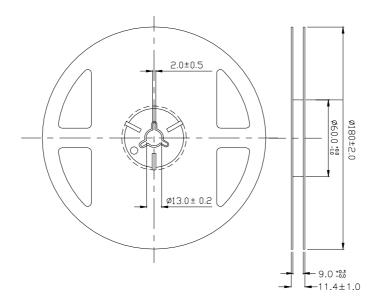
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank



Reel Dimensions

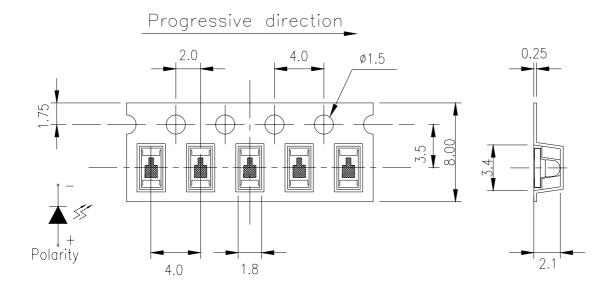


Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

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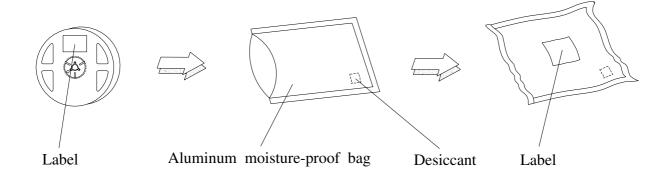
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Carrier Tape Dimensions: Loaded quantity 1500 PCS per reel



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Moisture Resistant Packaging



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Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	$H: +100^{\circ}\mathbb{C}$ 15min \int 5 min $L: -40^{\circ}\mathbb{C}$ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H:+100°C 5min ∫ 10 sec L:-10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85% RH	1000 Hrs.	22 PCS.	0/1

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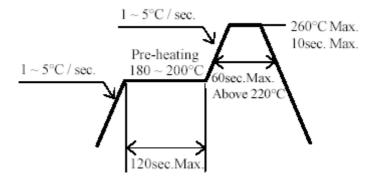
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Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: $60\pm5^{\circ}$ C for 24 hours.
- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

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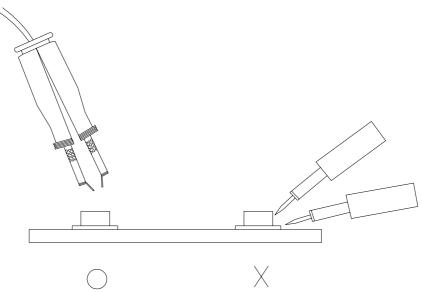


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



EVERLIGHT ELECTRONICS CO., LTD.

Office: No 25, Lane 76, Sec 3, Chung Yang Rd, Tucheng, Taipei 236, Taiwan, R.O.C Tel: 886-2-2267-2000, 2267-9936

Fax: 886-2267-6244, 2267-6189, 2267-6306

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